

L Number	Hits	Search Text	DB	Time stamp
-	1786	((conduct\$3 adj2 ink\$1) and (circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/09 15:38
-	103	((conduct\$3 adj2 ink\$1).clm. and (circuit adj board)) and printing.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/09 15:21
-	14	((conduct\$3 adj2 ink\$1).clm. and (circuit adj board) and (heating adj2 (substrate or circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/09 15:26
-	8	((conduct\$3 adj2 ink\$1).clm. and (circuit adj board) and ((substrate or circuit) adj heated))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/09 15:33
-	18	((conduct\$3 adj2 ink\$1).clm. and (circuit adj board) and (heating adj2 (substrate or circuit))) or (((conduct\$3 adj2 ink\$1).clm. and (circuit adj board) and ((substrate or circuit) adj heated)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/09 15:27
-	6	((circuit adj board) and ((substrate or circuit) adj \$3heated) with (prior or before) with print\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 15:51
-	338	((conduct\$3 adj2 ink\$1).clm. and (circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/09 15:38
-	183	((conduct\$3 adj2 ink\$1).clm. and (circuit adj board)) and heat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/09 15:38
-	1031	((conduct\$3 adj2 ink\$1) and (circuit adj board)) and heat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 13:23
-	260	((conduct\$3 adj2 ink\$1) and (circuit adj board).clm.) and heat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/09 15:44
-	182	(circuit adj board) and berg.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/09 15:45
-	519	((conduct\$3 adj2 ink\$1) and (circuit adj board)) and (\$4heat\$3 with (substrate or insulat\$3 or ceramic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 13:38
-	106	((conduct\$3 adj2 ink\$1) and (circuit adj board).ab.) and (\$4heat\$3 with (substrate or insulat\$3 or ceramic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 13:32
-	3	("3934334").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 13:32

	7	(conduct\$3 adj2 ink\$1) and (circuit adj board).ab. and \$4heat\$3 and ((inkjet or ink-jet or electrophotographic or electro-photographic or press or lithographic) adj2 print\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 13:44
	102	(conduct\$3 adj2 ink\$1) and (circuit adj board) and \$4heat\$3 and ((inkjet or ink-jet or electrophotographic or electro-photographic or press or lithographic) adj2 print\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 13:44
	2	(circuit adj board) and ((substrate adj (preheat\$3 or pre-heat\$3)) same mask\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 15:19
	319	(circuit adj board) and ((substrate near3 (heat\$3 or preheat\$3 or pre-heat\$3)) same mask\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 15:25
	9	(circuit adj board) and ((substrate near3 (heat\$3 or preheat\$3 or pre-heat\$3)) same (resist near2 ink\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 15:29
	127	(circuit adj board) and ((heat\$3 or preheat\$3 or pre-heat\$3) same (resist near2 ink\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 15:29
	1540	(circuit adj board) and heat\$3 and (resist near2 (ink or etch or mask))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 15:53
	32	((circuit adj board) and heat\$3 and (resist near2 (ink or etch or mask))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 16:06
	34	((circuit adj board).ti. or (circuit adj board).ab. or (circuit adj board).clm.) and (heat\$3 adj2 substrate) and (resist near2 (ink or etch or mask)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/16 16:15
	8	(\$3heat\$3 adj2 substrate) same (resist near2 (ink or etch or mask)) same print\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 11:32
	0	6709962.URPN.	USPAT	2004/08/16 16:18
	7	("4661431" "4737858" "4763157" "5382315" "5470644" "5489985" "6080606" "2002/0154187").PN.	USPAT	2004/08/16 16:18
	6	("4661431" "4763157" "5382315" "5470644" "5489985" "6080606" "2002/0028574" "2002/0154187").PN.	USPAT	2004/08/16 16:24
	6	(\$3heat\$3 near2 substrate) with (resist near2 (ink or etch or mask)) with print\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 11:40
	9	(\$3heat\$3 near2 substrate) same ((resist near2 (ink or etch or mask)) with print\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 11:42
	11	(\$3heat\$3 near2 (clad\$3 or copper or circuit)) same ((resist near2 (ink or etch or mask)) with print\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 11:44

-	310	\$3heat\$3 same ((resist near2 (ink or etch or mask)) with print\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 11:45
-	110	(circuit adj board) and (\$3heat\$3 same ((resist near2 (ink or etch or mask)) with print\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 11:45
-	13	4661431.URPN.	USPAT	2004/08/17 12:00
-	8	("2910351" "3071070" "3075866" "3650860" "3758327" "3856519" "3862848" "4373016").PN.	USPAT	2004/08/17 12:03
-	13	4661431.URPN.	USPAT	2004/08/17 12:05
-	13	(circuit adj board) and (\$3heat\$3 near2 substrate) same (toner with print\$3)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 14:18
-	1	2004-206796.NRAN.	DERWENT	2004/08/17 12:13
-	4	("2297691" "3239465" "3558492" "3681106").PN.	USPAT	2004/08/17 12:22
-	1	("3650860").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 12:22
-	0	(circuit adj board) and (\$3heat\$3 near2 substrate) same (resist with (inkjet or ink-jet))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 14:21
-	8	(circuit adj board) and (\$3heat\$3 near2 substrate) and (resist with (inkjet or ink-jet))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/17 14:21